Electronic Patent Application Fee Transmittal							
Application Number:	10549440						
Filing Date:	16-Sep-2005						
Title of Invention:	Copper alloy sputtering target process for producing the same and semiconductor element wiring						
First Named Inventor/Applicant Name:	Takeo Okabe						
Filer:	William Bak						
Attorney Docket Number:	00	OGOSH39USA					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Statutory disclaimer	1814	1	140	140
	Tot	140		